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**(54) MULTILAYER WIRING BOARD WITH BUILT-IN
PASSIVE COMPONENT AND MANUFACTURE
THEREOF**

1b, 1c, so that they are not in contact with each other.

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(57) Abstract:

PROBLEM TO BE SOLVED: To obtain a multilayer wiring board with built-in passive component and a method for manufacturing it, wherein the board can be manufactured by unifying and backing simultaneously the passive component and the multilayer wiring board and the passive component has desired characteristics.

SOLUTION: In this multilayer wiring board with a built-in passive component, the passive component including a dielectric layer 2 is built in the multilayer wiring board comprising board layers 1a-1d, which are insulators whose main component is inorganic material. An intermediate layer 3, including one oxide selected from magnesium oxide, zinc oxide, and calcium oxide, is interposed between the dielectric layer 2 and the board layers

